



TITAN

Vacuum Loadlocked Plasma System for Semiconductor Production



Titan shown with ICP option

A very compact, fully automated, vacuum loadlocked plasma system for semiconductor production. Available in either Reactive Ion Etch (RIE) configuration, High Density Inductive Coupled Plasma (HDICP) or Plasma Enhanced Chemical Vapor Deposition (PECVD) configuration. Used for advanced processing of single wafers or mounted parts. It also has multiple size batch capability. Small footprint at an affordable price.

Etch Applications

Gallium arsenide, aluminum gallium arsenide, gallium nitride, indium phosphide, aluminum, silicides, chrome and other materials requiring both corrosive and non-corrosive chemistries.

Deposition Applications

Silicon dioxide, silicon nitride, oxynitride and various other materials.

Trion has a fully equipped laboratory for process support both prior to and subsequent to purchase. For a more detailed discussion of applications and processes, please visit www.triontech.com.

Key Benefits & Features

High productivity

- The HDICP provides the user with high rate / high selectivity processing
- The Vacuum Cassette Elevator (VCE) pumps down the entire wafer cassette, which reduces particles and increases throughput
- The small system width provides very high throughput per linear foot in the fab

Production proven hardware

- Trion proven advanced, reliable, PLC and control system
- Trion Technology wafer transport module
- Small footprint
- Clean room interface

Easy maintenance

- Fast turn-around

State-of-the-art design concepts

- Modular design - more control hardware on-board
- Windows-based GUI
- Touchscreen input, 15.1" TFT monitor
- Embedded industrial computer - high reliability
- Bosch gas flow control option

High specification platform

- Single wafers or mounted parts: 3" - 300mm
- Multiple size batch capability: 4x3"; 3x4"; 7x2"
- Single vacuum cassettes with manual door
- Wafer mapping